



3D Printing Functionality: Materials, Sensors, Electromagnetics

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Message from the Guest Editor

Recently, there has been a rise in the commercial, industrial, and academic interest in the rapid prototyping technology, commonly referred to as additive manufacturing and 3D printing. Traditionally, additive technologies have been limited to purely mechanical applications. However, in recent years there has been a surge in advanced manufacturing investigations ranging from printed sensors and antennas to chemical and thermal functional materials. This additional functionality, incorporated with the ease and speed of traditional additive techniques, has the potential to revolutionize the production processes. It is expected that advances in functional printing techniques will drastically reduce time-to-market as well as improve overall device functionality.

As such, this Special Issue is intended to examine new techniques, designs, and processes that improve the functionality of printable and 3D printable devices or material systems. Of particular interest are topics that incorporate multiple means of functionality, whether through mechanical, thermal, electromagnetic, electrical, or chemical means.





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Message from the Editor-in-Chief

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